

Amendments to the Specification

Please amend the title as follows:

~~System and Method to Increase Throughput in a Dual Substrate Stage Double Exposure~~
Lithography System

Please amend paragraph [0001] as follows:

[0001] The present application is a continuation-in-part of U.S. Ser. No. 10/447,200 (now U.S. Patent No. 6,781,674 that issued August 24, 2004), filed May 29, 2003, which is incorporated by reference herein in its entirety.